

Industrial 3D TLC -290PC series PCIe-Chip® NVMe SSD

Product Manual

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www.cactus-tech.com

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Table of Contents

1.Introduction to Cactus Technologies® Industrial 3D TLC -290 Series NVEe SSD Products	
1.1.Supported Standards	
1.2.Product Features	
1.2.1.Host and Technology Independence	6
1.2.2.Defect and Error Management	6
1.2.3.Power Supply Requirements	7
	_
2.Product Specifications	
2.1.System Environmental Specifications	
2.3.System Performance	
2.4.System Reliability	
2.5.Physical Specifications	
2.5.1.PCIe-Chip® SSD Physical Specifications	
2.5.2.PCIe-Chip® SSD Solder Pad Recommendation	
3.PCIe-Chip® SSD Pin Assignments and Pin Type	10
	4.0
4. Electrical Specifications.	
4.1.1.Absolute Maximum Ratings	
4.1.2.DC Characteristics	
4.1.3.AC Characteristics	12
5.PCI Configuration	12
5.1.PCI Express Capabilities	
5.2.NVM Express Registers	
5.2.1.Controller Capabilities (CAP)	
5.2.2.Version (VS)	
5.2.3.Interrupt Mask Set (INTMS)	17
5.2.4.Interrupt Mask Clear (INTMC)	17
5.2.5.Controller Configuration (CC)	17
5.2.6.Controller Status (CSTS)	18
5.2.7.NVM Subsystem Reset (NSSR)	
5.2.8.Admin Queue Attributes (AQA)	
5.2.9.Admin Submission Queue Base Address (ASQ)	
5.2.10.Admin Completion Queue Base Address (ACQ)	
	10
6.1.Identify Command	19
6.1.Identify Controller Data Struture	19
7.SMART Reporting	
7.1.SMART Attributes	23
8.Device Features	24
9. Ordering Information	28
Appendix A Technical Support Services	29

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Appendix B.Cactus Technologies® Worldwide Sales Offices	30
Appendix C.Limited Warranty	31

1.Introduction to Cactus Technologies® Industrial 3D TLC -290 Series NVEe SSD Products

Features:

- Solid state design with no moving parts
- rugged, soldered down castellated PCB form factor (PCIe-Chip®)
- Capacities of 64/128/256/512GB
- Native NVMe interface
- Compliant with PCI Express base specifications, ver.3.1
- Compliant with NVMExpress specifications, ver.1.4
- PCI Express Gen3 x 2 configuration
- Supports ASPM L1.0, L1.1, L1.2
- Supports NVMe defined SMART attributes
- Supports 8 I/O gueues w/ max. gueue depth of 32 each
- LDPC error correction
- End-to-End datapath protection
- -40°C to 85°C operation
- Voltage support: 3.3V±5%

Cactus Technologies® Industrial 3D TLC NVMe SSD is a high capacity solid-state flash memory product in a solderable castellated PCB form factor that complies with the PCI Express base standard v3.1 and NVM Express v1.4 standard. It is a PCIe device that operates in native NVMe mode. Cactus Technologies® Industrial 3D TLC NVMe SSD provides up to 512GB of formatted storage capacity.

Cactus Technologies® Industrial 3D TLC NVMe SSD product uses high quality industrial grade 3D TLC (gTLC) NAND flash memory from Kioxia Corporation. In addition, it includes an ondrive intelligent controller that manages interface protocols, data storage and retrieval as well as ECC, defect handling and diagnostics, power management, and clock control. The controller's firmware is upgradeable, thus allowing feature enhancements and firmware updates while keeping the BOM stable.

1.1. Supported Standards

Cactus Technologies® NVMe SSD is fully compatible with the following specification:

- PCI Express base specification, ver. 3.1, published by PCI-SIG
- NVM Express Specification 1.4 published by NVM Express Organization

1.2. Product Features

Cactus Technologies[®] Industrial 3D TLC NVMe SSD contains a high level, intelligent controller. This intelligent controller provides many capabilities including the following:

- Standard NVMe register and command set
- Manages details of erasing and programming flash memory independent of the host system
- Sophisticated defect managing capabilities (similar to magnetic disk drives).
- Sophisticated system for error recovery using powerful error correction code (ECC).
- Intelligent power management for low power operation.

1.2.1. Host and Technology Independence

Cactus Technologies® Industrial 3D TLC NVMe SSD operates in native NVMe mode. To write or read to the device, the host computer software simply issues a PCI memory Read or Write command to the drive as per the PCI Express protocol. The host software then waits for the command to complete. The host system does not get involved in the details of how the flash memory is erased, programmed or read as this is all managed by the built-in controller in the drive. Also, with the intelligent on-board controller, the host system software will not require changing as new flash memory evolves. Thus, systems that support the Cactus Technologies® Industrial 3D TLC NVMe SSD products today will continue to work with future Cactus Technologies® Industrial 3D TLC NVMe SSDs built with new flash technology without having to update or change host software.

1.2.2. Defect and Error Management

Cactus Technologies® Industrial 3D TLC NVMe SSD contains a sophisticated defect and error management system similar to those found in magnetic disk drives. The defect management is completely transparent to the host and does not consume any user data space.

The soft error rate for Cactus Technologies® Industrial 3D TLC NVMe SSD is much lower than that of magnetic disk drives. In the extremely rare case where a read error does occur, the drive has sophisticated ECC to recover the data.

These defect and error management systems, coupled with the solid-state construction, give Cactus Technologies[®] Industrial 3D TLC NVMe SSDs unparalleled reliability.

1.2.3. Power Supply Requirements

Cactus Technologies $^{\circ}$ Industrial 3D TLC NVMe SSD operates at a voltage range of 3.3 volts \pm 5%.

2. Product Specifications

For all the following specifications, values are defined at ambient temperature and nominal supply voltage unless otherwise stated.

2.1. System Environmental Specifications

Table 2-1. Environmental Specifications

		Cactus Technologies® Industrial 3D TLC NVMe SSD
Temperature	Operating:	0°C to 70°C (standard temp.) -40° C to +85° C (extended temp.)
Humidity	Operating & Non- Operating:	8% to 95%, non-condensing
Vibration	Operating & Non- Operating:	16.4G, MIL-STD-810F Method 514.5, Procedure 1
Shock	Operating & Non- Operating:	50 G, MIL-STD-810F Method 516.5, Procedure 1
Altitude (relative to sea level)	Operating & Non- Operating:	100,000 feet maximum

2.2. System Power Requirements

Table 2-2. Power Requirements

		Cactus Te	echnologie NVMe	s [®] Industri e SSD	al 3D TLC
		64GB	128GB	256GB	512GB
DC Input Voltage (VCC) 100 mV max. ripple (p-p)			3.3V	±5%	
(Maximum Average Value) See Notes.	Idle:	330mA	330mA	330mA	330mA
000 1101001	Read:	560mA	690mA	740mA	700mA
	Write	500mA	580mA	770mA	770mA

NOTES: All values quoted are typical at ambient temperature and nominal supply voltage unless otherwise stated.

Idle mode is specified under the condition that all drive inputs are static CMOS levels and in a "Not Busy" operating state.

2.3. System Performance

All performance timings are for 25C with the drive controller in the default fastest mode(i.e. with SLC cache active.

Note:

- 1. Due to the high throughput of PCIe interface, the drive controller implements thermal throttling to prevent excessive die temperature which will damage the device. Thermal throttling will kick in when internal die temperature reaches 90°C. The drive's rd/wr performance will drop significantly when thermal throttling kicks in. It is advised that the user apply a heatsink to the module and provide adequate air flow in their system to reduce the likelihood of thermal throttling from happening.
- 3D NAND SSD operates natively in TLC mode. To boost write performance, a SLC cache partition is used. Once this SLC cache partition is full, write throughput will drop substantially. For -290PC series NVMe SSD, the SLC cache size is approx. 1/3 drive capacity.

64GB 128G 256G 512G Seq. Read 659MB/s 1.29GB/s 1.44GB/s 1.12GB/s Seq. Wr 318MB/s 623MB/s 1.23GB/s 1.15GB/s Random 4K read IOPS 12000 21000 36000 32000 Queue depth=32 Random 4K write IOPS 21000 42000 11000 45000 Queue depth=32

Table 2-3. Performance

2.4. System Reliability

Table 2-4. Reliability

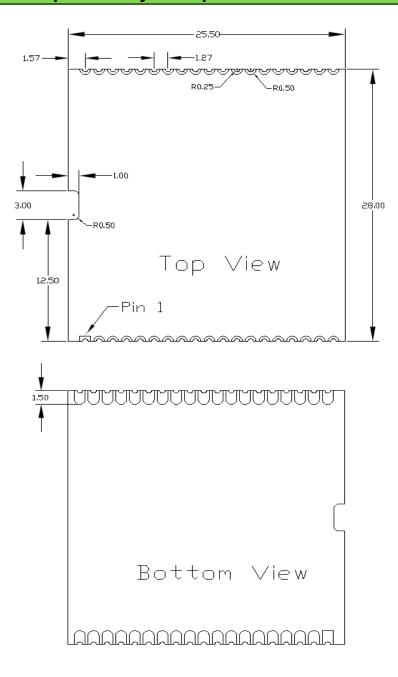
Data Reliability	$<$ 1 non-recoverable error in 10^{14} bits READ
Endurance (estimated TBW):	Up to:
64GB	192TB
128GB	384TB
256GB	768TB
512GB	1536TB

Note: estimated TBW assumes workload consisting of mostly large block writes; estimated TBW will be significantly reduced for workloads consisting of mostly random, small block writes. Data retention requirements are not considered in this estimation.

2.5. Physical Specifications

The following sections provide the physical specifications for Cactus Technologies® Industrial 3D TLC NVMe SSD products.

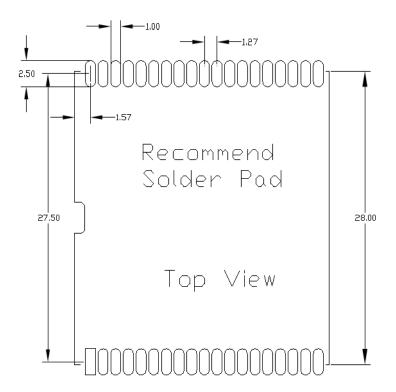
2.5.1. PCle-Chip® SSD Physical Specifications



2-1. PCle-Chip®SSD Dimensions

2.5.2. PCIe-Chip® SSD Solder Pad Recommendation

The following diagram shows the recommendation for solder pad dimensions to use for PCB production:





3.PCIe-Chip[®] SSD Pin Assignments and Pin Type

The signal/pin assignments and descriptions are listed below. Note that the pinout definitions are from the perspective of the device.

Pin #	Pin Name	Description	Pin #	Pin Name	Description
1	GND		38	GND	
2	REFCLKp	PCIe Reference Clock Input	37	3.3V	
3	REFCLKn		36	3.3V	
4	GND		35	NC	

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Pin #	Pin Name	Description	Pin #	Pin Name	Description
5	PORXP	Channel 0 Receive	34	GND	
6	PORXM	Input to device	33	GND	
7	GND		32	DAS/DSS	LED for Drive activity
8	P0TXM	Channel 0 Transmit	31	NC	
9	POTXP	Output from device	30	NC	
10	GND		29	PERSTn	
11	P1RXP	Channel 1 Receive	28	CLKREQn	
12	P1RXM	Input to device	27	NC	
13	GND		26	GND	
14	P1TXM	Channel 1 Transmit	25	GND	
15	P1TXP	Output from device	24	NC	
16	GND		23	NC	
17	3.3V		22	3.3V	
18	3.3V		21	3.3V	
19	GND		20	GND	

4. Electrical Specifications

The following table defines all D.C. Characteristics for the NVMe SSD products. Unless otherwise stated, conditions are:

 $Vcc = 3.3V \pm 5\%$ Ta = -40°C to 85°C

4.1.1. Absolute Maximum Ratings

Parameter	Symbol	MIN	MAX	Unit s
Storage Temperature	Ts	-55	100	°C
Operating Temperature	T _A	-40	85	°C
Vcc with respect to GND	Vcc	-0.3	3.6	V

4.1.2. DC Characteristics

Parameter	Symbol	MIN	MAX	Unit s
Input Voltage	Vin	-0.5	Vcc + 0.5	V
Output Voltage	Vout	-0.3	Vcc + 0.3	V
Input Leakage Current	lμ	-10	10	uA
Output Leakage Current	I _{LO}	-10	10	uA
Input/Output Capacitance	C _I /C _o		10	рF
Operating Current	I _{cc}			mA
Idle			335	
Active			775	

4.1.3. AC Characteristics

Cactus Technologies® NVMe SSD products conforms to all AC timing requirements as specified in the PCI Express base specifications. Please refer to that document for details of AC timing for all operation modes of the device.

5.PCI Configuration

Cactus Technologies® NVMe SSD is a PCIe device. The following table shows the PCI Configuration Register values for this device:

address	Bit[31:24]	Bit[23:16]	Bit[15:8]	Bit[7:0]	
00h	Device ID :	Device ID : 5765h Vendor ID: 1E3Ah): 1E3Ah	
04h	Status: 001	.0h	Command	nd	
08h	Class Code	: 010802h		Revision ID:	
	Mass Stora	ge Controlle	er	01h	
	Non-volatile	e Memory			
	NVM Expre	ss			
0Ch	BIST	Header Type: 00h	Latency Timer:	Cacheline Size	
10h					
14h		Base Address Registers			
18h					
1Ch					
20h					
24h					
28h		Cardbus CIS	6 Pointer: N	N/A	
2Ch	Subsystem ID: 5765h Subsystem Vendor ID: 1E3Ah			m Vendor ID:	
30h	Expansion ROM Base Address				
34h	Reserved Capabilities Pointer: 40h				
38h	Reserved				
3Ch	Max Lat: 01h	Min Gnt: 0bh	Interrupt Pin	Interrupt Line	

5.1. PCI Express Capabilities

Cactus Technologies® Industrial 3D TLC grade NVMe SSD supported PCI Express capabilities are listed in the following table, please consult PCI Express Specifications for detailed explanation of the capabilities:

Capability	Register	Description
PCI Express		Ver. 2; PCIe Endpoint
	Device Capabilities	Max. payload size: 512 bytes Phantom Function: Not Supported Extended Tag Field: supported EndPoint L0s latency: unlimited EndPoint L1 latency: unlimited Role-based Error Reporting: supported Slot Power Limit: 75W Function Level Reset: supported
	Device Control	Set by host
	Device Status	Reported Status: Correctable Error Detected, Non-Fatal Error Detected, Fatal Error Detected, Unsupported Request Detected, Aux Power Detected, Transaction Pending
	Link Capabilities	8GT/s, 4 lanes; ASPM L1 supported; L0s Exit Latency: > 4us; L1 Exit Latency: > 64us; Clock Power Management: supported Surprise Down Error Reporting: not supported Data Link Layer Link Active Reporting: not supported Link Bandwidth Notification: not supported ASPM: supported
	Link Control	Set by host
	Link Status	Reported Status: Current Link Speed, Negotiated Link Width, Slot Clock Configuration
	Device Capabilities 2	Completion Timeout Range: not supported Completion Timeout Disable: supported 32/64 bit Atomic Op Completer: not supported 128 bit CAS Completer: not supported Latency Tolerance Reporting: supported TPH/Extended TPH Completer: not supported OBFF: supported using message or WAKE# Extended Fmt Field: not supported End-to-End TLP Prefix: not supported
	Device Control 2	Set by host
	Link Capabilities 2	Supported Link Speeds: 2.5/5.0/8.0 GT/s; Crosslinks: not supported
	Link Control 2	Set by host
	Link Status 2	Reported Status: Current De-emphasis Level, Equalization Complete, Equalization Phase 1 Successful, Equalization Phase 2 Successful, Equalization Phase 3 Successful, Link Equalization Request

Capability	Register	Description
MSI		64-bit address: supported Per vector masking: not supported
MSI-X		MSI-X table size: 9
Power Management		Complies with v3 of PCI Power Management Interface DSI: not required PME Clock: PCI Clk not required to generate PME# D1, D2, PME: not supported Aux Current: not supported
	Power Management Control/Status	Reported Status: Power State, No_Soft_Reset, Data Scale
Extended Capabilities	Latency Tolerance Reporting	Capability version 1; Max Snoop Latency: 71680ns; Max No-Snoop Latency: 71680ns
	L1 PM Substate	Version 1 PCI-PM L1.1, L1.2: supported ASPM L1.1, L1.2: supported L1 PM Substates: supported Port Common Mode Restore Time: 60us Port T_Power_On Value: 60us
	L1 PM Substate Control 1	Set by host
	L1 PM Substate Control 2	Set by host
	Advanced Error Reporting	Capability version 2 Implemented Registers: Uncorrectable Error Status, Uncorrectable Error Mask, Uncorrectable Error Severity, Correctable Error Status, Correctable Error Mask, Advanced Error Capabilities and Control, Header Log
	Device Serial Number	Capability version 1 Serial number: 0000001004cec00h
Secondary PCI Express Extended Capability		Capability version 1
	Link Control 3	Set by host
	Lane Error Status	
	Lane Equalization Control	Set by host, one register per lane

5.2. NVM Express Registers

The following sections describe the NVMe register contents of Cactus Technologies® Industrial 3D TLC grade NVMe SSD.

5.2.1. Controller Capabilities (CAP)

This 64-bit register indicates basic capabilities of the controller.

Bit(s)	Name	Value	Description		
63:58			Reserved		
57	CBMS	0	Controller Memory Buffer: not supported		
56	PMRS	0	Persistent Memory Region: not supported		
55:52	MPSMAX	0	Memory Page Size Max: 4096		
51:48	MPSMIN	0	Memory Page Size Min: 4096		
47:46			Reserved		
45	BPS	0	Boot Partition: not supported		
44:37	CSS	1	Command Set Supported: NVM command set, I/O command set		
36	NSSRS	0	NVMe Subsystem Reset Supported: No		
35:32	DSTRD	0	Doorbell Stride: 4 bytes, this indicates there is no gap between doorbells registers		
31:24	то	78h	TimeOut for CSTS.RDY to switch states: 20s		
23:19			Reserved		
18:17	AMS	00	Arbitration Mechanism Supported: Round robin		
16	CQR	1	Contiguous Queue Required. I/O submission and completions queues must be physically contiguous.		
15:0	MQES	03FFh	Max. Queue Entries Supported for I/O queues: 1024		

5.2.2. Version (VS)

This 32-bit register indicates the NVMe Specification supported by the device. Cactus Technologies[®] Industrial 3D TLC grade NVMe SSD supports NVMe Specification v1.4.

Bit(s)	Name	Value	Description	
31:16	MJR	0001h	Major Version Number: 1	
15:8	MNR	03h	Minor Version Number: 4	
7:0	TER	0	Tertiary Version Number: 0	

5.2.3. Interrupt Mask Set (INTMS)

This 32-bit register is used to mask interrupts if legacy or MSI interrupts are used, this register is not used if MSI-X interrupts are used.

Bit(s)	Name	Value	Description	
31:0	IVMS		Interrupt Vector Mask Set. Each bit that is set to '1' masks the corresponding interrupt vector.	

5.2.4. Interrupt Mask Clear (INTMC)

This 32-bit register is used to clear interrupt masks if legacy or MSI interrupts are used, this register is not used if MSI-X interrupts are used.

Bit(s)	Name	Value	Description	
31:0	IVMC		Interrupt Vector Mask Clear. Each bit that is set to '1' clears the corresponding interrupt vector mask.	

5.2.5. Controller Configuration (CC)

This 32-bit register is written by the host to modify settings for the drive controller.

Bit(s)	Name	Value	Description	
31:24			Reserved	
23:20	IOCQES		I/O Completion Queue Entry Size	
19:16	IOSQES		I/O Submission Queue Entry Size	
15:14	SHN		Shutdown Notification	
13:11	AMS		Arbitration Mechanism Selection	
10:7	MPS		Memory Page Size	
6:4	CSS		I/O Command Set Selection	

Bit(s)	Name	Value	Description	
3:1			Reserved	
0	EN		Enable. Host writes '1' to this bit to enable the device to start processing commands.	

5.2.6. Controller Status (CSTS)

This 32-bit register provides status information of the drive controller.

Bit(s)	Name	Value	Description	
31:6			Reserved	
5	PP		Process Paused. When set to '1', it indicates the drive controller has stopped processing commands	
4	NSSRO		NVM Subsystem Reset Occurred. When set to '1', it indicates a reset has occurred while powered up.	
3:2	SHST		Shutdown Status. 00b: Normal, no shutdown requested; 01b: shutdown processing occuring; 10b: shutdown processing complete; 11b: reserved	
1	CFS		Controller Fatal Status. A value of '1' indicates a fatal controller error has occurred.	
0	RDY		Ready. A value of '1' indicates the drive controller is ready to accept commands	

5.2.7. NVM Subsystem Reset (NSSR)

Host writes a value of 4E564D65h to this register to request a NVM Susbsystem Reset. A write of any other values to this register has no effect. A read of this register always returns zeroes. This register is supported only if the NSSRS bit is set.

5.2.8. Admin Queue Attributes (AQA)

This 32-bit register contains attributes for the Admin Submission and Completion queues.

Bit(s)	Name	Value	Description
31:28			Reserved
27:16	ACQS		Admin Completion Queue Size: 32
15:12			Reserved
11:0	ASQS		Admin Submission Queue Size: 32

5.2.9. Admin Submission Queue Base Address (ASQ)

This 64-bit register is written by the host to set the Admin Submission Queue Base Address.

5.2.10. Admin Completion Queue Base Address (ACQ)

This 64-bit register is written by the host to set the Admin Completion Queue Base Address.

6.Identify Command

The Identify command is an Admin command that retrieves information about the NVM subsystem. The returned structure is 4096 bytes and the following section describes the contents of this structure in Cactus Technologies® Industrial 3D TLC grade NVMe SSDs.

6.1. Identify Controller Data Struture

Byte(s)	Name	Value	Description
1:0	VID	1E3Ah	PCI Vendor ID. This is PCISIG assigned Vendor ID for Cactus Technologies®
3:2	SSVID	1E3Ah	PCI Subsystem ID.
23:4	SN	varies	This field returns product specific serial number. For this product, the serial number has the format 'KD290PC XXXXXXXX'
63:24	MN	Fixed	This field returns manufacturer's name. For this product, the returned string is: CactusFlashCard
71:64	FR	varies	Firmware version.
72	RAB	0	Recommended Arbitration Burst size in bytes.
75:73	IEEE	-	IEEE OUI Identifier. Not applicable for this product.
76	CMIC	0	Controller Multipath I/O and Namespace Sharing Capacbilities: Single Port, Single Controller, PCI function
77	MDTS	5	Max. Data Transfer Size: 2^5 x MPSMIN
79:78	CNTLID	1	Controller ID.
83:80	VER	10400h	Version: NVM Express 1.40
87:84	RTD3R	7A120h	RTD3 Resume Latency. Resume time from Runtime D3: 500ms
91:88	RTD3E	1E8480 h	RTD3 Entry Latency. Latency to enter Runtime D3: 2s
95:92	OAES	300h	Optional Asynchronous Events Supported: Firmware Activation Notices, Namespace Attribute Changed
99:96	CTRATT	2h	Controller Attributes: Non-operational State Power State Permissive Mode supported
101:100	RRLS	0h	Not applicable. Read Recovery is not supported
102:110			Reserved
111	CNTRLTYPE	1h	I/O Controller
127:112	FGUID	0	Not applicable. IEEE assigned OUI
129:128	CRDT1	0	Command Retry Delay 1; not applicable

Byte(s)	Name	Value	Description
131:130	CRDT2	0	Command Retry Delay 2; not applicable
133:132	CRDT3	0	Command Retry Delay 3; not applicable
241:14:00			Reserved
259:00:00		0	Management Endpoint Capabilities: none
257:256	OACS	17h	Optional Admin Command Support:
			Security Send & Receive commands: supported
			Format NVM command: supported
			Firmware commit and Download: supported
			Device Self-test: supported
258	ACL	7	Abort Command Limit
259	AERL	3	Asynchronous Event Request Limit
260	FRMW	2h	Firmware Updates: Firmware Slot 1 Rd/Wr; 1 firmware slots; firmware activation without reset not supported
261	LPA	2h	Log Page Attributes: Command Effects Log page supported,
262	ELPE	7	Error Log Page Entries
263	NPSS	4	Number of Power States Support
264	AVSCC	1	Admin Vendor Specific Command Configuration: NVMe format
265	APSTA	1	Autonomous Power State Transition Attributes: Autonomous Power State Transition supported
267:266	WCTEMP	373	Warning Composite Temperature Threshold: 373K (100C)
269:268	ССТЕМР	353	Critical Compostie Temperature Threshold: 383K (110C)
271:270	MTFA	150	Max. Firmware Activation Time: 15s
275:272	HMPRE	0	Host Memory Buffer Prefer Size: 64MB
279:276	HMMIN	0	Host Memory Buffer Min. Size: 32MB
295:280	TNVMCAP	0	Total NVM Capacity: Not reported as Namespace Mangement & Attachment commands are not supported
311:296	UNVMCAP	0	Unallocated NVM Capacity: not reported
315:312	RPMBS	0	Replay Protected Memory Block Support: not supported
317:316	EDSTT	5	Extended Device Self-test Time: 5 mins
318	DSTO	1	Device Self-test Option: one device self-test operation at a time
319	FWUG	1	Firware Update Granularity: 4KB
321:320	KAS	1200	Keep Alive Support: 120s
323:322	HCTMA	1	Host Controlled Thermal Management Attribute: supported
325:324	MNTMT	318	Min. Thermal Management Temperature: 45C
327:326	MXTMT	393	Max. Thermal Management Temperature: 120C
331:328	SANICAP	2	Sanitize Capabilities:
			Block Erase Sanitize supported
			No Deallocate After Sanitize not supported Media is modified after sanitize
335:332	HMMINDS	0	HMB Min. Descriptor Entry Size: No limit
337:336	HMMAXD	0	HMB Max. Descriptor Entries: No limit
339:338	NSETIDMAX	0	Max. value of NVM Set Identifier
341:340	ENDGIDMAX	0	Max. value of Endurance Group Identifier
342	ANATT	0	Not applicable; ANA not supported
343	ANACAP	0	ANA not supported

Byte(s)	Name	Value	Description
347:344	ANAGRPMAX	0	ANA Group Identifier Max. Not applicable, ANA not supported
351:348	NANAGRPID	0	Number of ANA Group Identifier. Not applicable, ANA not supported
355:352	PELS	0	Persistent Event Log Size. Not applicable; PEL not supported
511:356			Reserved
512	SQES	66h	Submission Queue Entry Size. Required: 64, Max: 64
513	CQES	44h	Completion Queue Entry Size. Required: 16, Max: 16
515:514	MAXCMD	4	Max Outstanding Command: 4
519:516	NN	1	Number of Namespaces: 1
521:520	ONCS	5Eh	Optional NVM Command Support:
			Write Uncorrectable Command: supported
			Dataset Management Command: supported
			Write Zeroes Command: supported
			Save and Select Fields: supported
			Timestamp: supported
523:522	FUSES	0	Fused Operation Support: Fused Compare and Write operation not supported
524	FNA	0	Format NVM Attributes: Format applies to single namespace, Crypto and user data erase applies to single namespace, Cryptoerase not supported as part of Secure Erase
525	VWC	5	Volatile Write Cache: present; Flush command does not support NSID set to FFFFFFFh
527:526	AWUN	0	Atomic Write Unit Normal: size of write unit guaranteed to be written atomically during normal operation
529:528	AWUPF	0	Atomic Write Unit Power Fail: size of write unit guaranteed to be written atomically during power fail or error condition
530	NVSCC	1	NVM Vendor Specific Command Configuration: NVMe format
531	NWPC	0	Write Protect not supported
533:532	ACWU	0	Atomic Compare & Write Unit: size of write unit guaranteed to be written atomically during a fused compare and write operation
535:534			Reserved
539:536	SGLS	0	SGL Support: not supported
543:540	MNAN	0	Max. number of Allowed Namespaces; same as NN field
776:04:00			Reserved
1023:768	SUBNQN		NVM Subsystem NVMe Qualified Name: vendor specific
2047:1024			Reserved

Byte(s)	Name	Value	Description
2079:2048	PSD0		Power State 0 Descriptor:
			Max Power (MP): 8W
			Non-Operational State (NOPS): I/O commands operational
			Entry Latency (ENLAT): 230ms
			Exit Latency (EXLAT): 50ms
			Relative Read Throughput (RRT): 0
			Relative Read Latency (RRL): 0
			Relative Write Throughput (RWT): 0
			Relative Write Latency (RWL): 0
			Idle Power (IDLP): not reported
			Active Power (ACTP): not reported
2111:2080	PSD1		Power State 1 Descriptor:
			Max Power (MP): 4W
			Non-Operational State (NOPS): I/O commands operational
			Entry Latency (ENLAT): 4ms
			Exit Latency (EXLAT): 50ms
			Relative Read Throughput (RRT): 1
			Relative Read Latency (RRL): 1
			Relative Write Throughput (RWT): 1
			Relative Write Latency (RWL): 1
			Idle Power (IDLP): not reported
			Active Power (ACTP): not reported
2143:2112	PSD2		Power State 2 Descriptor:
			Max Power (MP): 3W
			Non-Operational State (NOPS): I/O commands operational
			Entry Latency (ENLAT): 4ms
			Exit Latency (EXLAT): 250ms
			Relative Read Throughput (RRT): 2
			Relative Read Latency (RRL): 2
			Relative Write Throughput (RWT): 2
			Relative Write Latency (RWL): 2
			Idle Power (IDLP): not reported
			Active Power (ACTP): not reported
2175:2144	PSD3		Power State 3 Descriptor:
			Max Power (MP): 0.03W
			Non-Operational State (NOPS): I/O commands non- operational
			Entry Latency (ENLAT): 5ms
			Exit Latency (EXLAT): 10ms
			Relative Read Throughput (RRT): 3
			Relative Read Latency (RRL): 3
			Relative Write Throughput (RWT): 3
			Relative Write Latency (RWL): 3
			Idle Power (IDLP): not reported
			Active Power (ACTP): not reported

Byte(s)	Name	Value	Description
2207:2176	PSD4		Power State 4 Descriptor:
			Max Power (MP): 0.005W
			Non-Operational State (NOPS): I/O commands not operational
			Entry Latency (ENLAT): 54ms
			Exit Latency (EXLAT): 45ms
			Relative Read Throughput (RRT): 4
			Relative Read Latency (RRL): 4
			Relative Write Throughput (RWT): 4
			Relative Write Latency (RWL): 4 Idle Power (IDLP): not reported Active Power (ACTP): not reported
4095:2208			Reserved

7.SMART Reporting

Cactus Technologies® Industrial 3D TLC NVMe SSD supports SMART attribute reporting in the SMART Log Page using the Get Log Page Admin command. The attributes reported are shown below.

7.1. SMART Attributes

The following attributes are reported in the SMART Log page:

Attribute	Description
Critical Warning	Bit 0: if set to '1', this indicates available spare has fallen below threshold
	Bit 1: if set to '1', this indicates temperature has exceeded high temperature threshold or dropped below low temperature threshold
	Bit 2: if set to '1', this indicates excessive media error
	Bit 3: if set to '1', this indicates the drive is in read only mode
	Bit[7:4]: reserved
Temperature	Temperature in Kelvin
Available Spare	Percentage remaining spares
Available Spare Threshold	Warning flag is set if remaining spares drops below this threshold percentage
Percentage Used	This is a vendor specific estimation of the percentage life used for the device
Endurance Group Critical Warning Summary	Bit 0: if set to '1', the available spare capacity of one or more endurance group has fallen below threshold Bit 1: reserved Bit 2: if set to '1', the reliability of one or more endurance group has degraded Bit 3: if set to '1', the namespaces in one or more endurance group have been placed in read only mode Bit[7:4]: reserved
Data Units Read	Number of 512bytes units read; each count represents 1000 units
Data Units Written	Number of 512bytes units written; each count represents 1000 units
Host Read Commands	Number of host read commands processed

Attribute	Description
Host Write Commands	Number of host write commands processed
Controller Busy Time	The amount of time the drive is busy processing I/O commands; the unit is in minutes
Power Cycles	Number of power cycles
Power On Hours	Number of Power On Hours
Unsafe Shutdowns	The number of power loss without prior Shutdown notification.
Media and Data Integrity Errors	Number of uncorrectable data errors
Number of Error Information Log Entries	Number of Error Information Log Entries over the product's life
Warning Composite Temperature Time	Amount of time in minutes that the drive is in operation above the Warning Temperature Threshold but below the Critical Temperature Threshold
Critical Composite Temperature Time	Amount of time in minutes that the drive is in operation above the Critical Temperature Threshold
Thermal Management T1 Trans Count	The number of times the controller has switched to lower power state due to composite temperature rising above thermal management temperature 1
Thermal Management T2 Trans Count	The number of times the controller has switched to lower power state due to composite temperature rising above thermal management temperature 2
Thermal Management T1 Total Time	The number of seconds the controller has switched to lower power state due to composite temperature rising above thermal management temperature 1
Thermal Management T2 Total Time	The number of seconds the controller has switched to lower power state due to composite temperature rising above thermal management temperature 2

8. Device Features

Features supported by Cactus Technologies® Industrial 3D TLC NVMe SSD are reported using the Get Features Admin command. The supported features are listed below:

Identifier	Name	Reset Value	Description
1	Arbitration	0	This feature controls command arbitration.
			Bit[31:24]: High Priority Weight (HPW). This defines the number of commands that can be executed from the High Priority service class in each arbitration round.
			Bit[23:16]: Medium Priority Weight (MPW). This defines the number of commands that can be executed from the Medium Priority service class in each arbitration round.
			Bit[15:08]: Low Priority Weight (LPW). This defines the number of commands that can be executed from the Low Priority service class in each arbitration round.
			Bit[7:3]: Reserved
			Bit [2:0]: Arbitration Burst (AB). This indicates the max. number of commands the controller can launch at one time from a Submission Queue. Value specified is 2^n.
2	Power - Management	This feature is used by the host to control the device power state. The returned content reflects the current power state attributes.	
			Bit[31:8]: Reserved
			Bit [7:5]: Workload Hint (WH). This field indicates the type of workload expected; this is set by the host with the Set Feature command.
			Bit[4:0]: Power State (PS). This field indicates the power state the device should transition to. This is set by the host with the Set Feature command.
4	Temperature	175h	Bit[31:22]: Reserved
	Threshold		Bit[21:20]: Threshold Type Select (THSEL) - over temperature threshold
			Bit[19:16]: Threshold Temperature Select (TMPSEL) - composite temperature
			Bit[15:0]: Temperature Threshold (TMPTH). 373K (100C)

Identifier	Name	Reset Value	Description
5	Error Recovery	0	This field reflects Error Recovery options as set by the host.
			Bit[31:17]: Reserverd
			Bit[16]: Deallocated or Unwritten Logical Block Error Enable (DULBE) – not enabled
			Bit[15:0]: Time Limited Error Recovery (TLER) - No timeout
6	Volatile Write Cache	1	Volatile Write Cache Enable (WCE). This field reflects the state of Volatile Write Cache as set by the host.
			Bit[31:1]: Reserved
			Bit[0]: If set, Volatile Write Cache is enabled.
7	Number of Queues		Bit[31:16]: On writes, this is the umber of I/O Completion Queue requested by the host (NCQR). On reads, this is the number of I/O Completion Queue allocated.
			Bit[15:0]: On writes, this is the number of I/O Submission Queue requested by the bost (NSQR). On reads, this is the number of I/O Submission Queue allocated (NSQA).
8	Interrupt Coalescing	0	Bit[31:16]: Reserved
			Bit[15:8]: Aggregation Time (TIME). Max. time in 100us units that the controller can delay an interrupt. 0 indicates no delay.
			Bit[7:0]: Aggregation Threshold (THR). This indicates the min. number of completion queue entries to aggregrate before interrupting the host, value is n+1.
9	Interrupt Vector Configuration	0 ation	This field returns status of Interrupt Vector Configuration as set by the host.
			Bit[31:17]: Reserved
			Bit[16]: Coalescing Disable (CD). If set to 1, interrupt coalescing is disabled for the Interrupt Vector indicated in bit[15:0].
			Bit[15:0]: Interrupt Vector (IV). This field indicates the Interrupt Vector applicable to this configuration.

Identifier	Name	Reset Value	Description
10	Write Atomicity Normal	0	This field reflects the opertions of AWUN and NAWUN parameters as set by the host.
			Bit[31:1]: Reserved
			Bit[0]: Disable Normal (DN). If set to 1, controller are not required to honor AWUN and NAWUN.
11	Asynchronous Event Configuration	0	This field controls asynchronous event reporting as set by the host.
			Bit[31:10]: Reserved
			Bit[9]: Firmware Activation Notice. If set, firmware activation notices are to be sent to the host.
			Bit[8]: Namespace Attribute Notice. If set, namespace attribute change event notices are to be sent to the host.
			Bit[7:0]: SMART Critical Warning. If set, each corresponding critical warning bit in SMART Log will trigger notice to the host.
12	Autonomous Power State Transition	wer State	This feature reports power state transition settings.
			Bit[31:1]: Reserved.
			Bit[0]: Autonomous Power State Transition Enable (ASPTE). If cleared, Autonomous Power State Transition is disbaled. If set, transition attributes for each power state is returned in the Autonomous Power State Transition Structure.

9. Ordering Information

Model KDXFY-290PC

Where: X is drive capacities:
64G 64GB
128G 128GB
256G 256GB
512G 512GB
Where: Y is temperature grade Blank standard temp. I extended temp.
Example:
1. KD128GF-290PC 128G standard temp. SSD
2. KD256GFI-290PC

Appendix A.Technical Support Services A.1.Direct Cactus Technologies® Technical Support

Email: tech@cactus-tech.com

Appendix B.Cactus Technologies® Worldwide Sales Offices

Email: sales@cactus-tech.com

Email: americas@cactus-tech.com

Appendix C.Limited Warranty

I. WARRANTY STATEMENT

Cactus Technologies® warrants its Industrial Grade products only to be free of any defects in materials or workmanship that would prevent them from functioning properly for two years from the date of purchase or when rated TBW is exceeded, whichever occurs first. This express warranty is extended by Cactus Technologies® Limited to customers of our products.

II. GENERAL PROVISIONS

This warranty sets forth the full extent of Cactus Technologies® responsibilities regarding the Cactus Technologies® Industrial 3D TLC Grade Flash Storage Products. Cactus Technologies®, at its sole option, will repair, replace or refund the purchase price of the defective product. Cactus Technologies® guarantees our products meet all specifications detailed in our product manuals. Although Cactus Technologies® products are designed to withstand harsh environments and have the highest specifications in the industry, they are not warranted to never have failure and Cactus Technologies® does not warranty against incidental or consequential damages. Accordingly, in any use of products in life support systems or other applications where failure could cause injury or loss of life, the products should only be incorporated in systems designed with appropriate redundancy, fault tolerant or backup features.

III. WHAT THIS WARRANTY COVERS

For products found to be defective, Cactus Technologies® will have the option of repairing, replacing or refunding the purchase price the defective product, if the following conditions are met:

- A. The defective product is returned to Cactus Technologies® for failure analysis as soon as possible after the failure occurs.
- B. An incident card filled out by the user, explaining the conditions of usage and the nature of the failure, accompanies each returned defective product.
- C. No evidence is found of abuse or operation of products not in accordance with the published specifications, or of exceeding maximum ratings or operating conditions.

All failing products returned to Cactus Technologies® under the provisions of this limited warranty shall be tested to the product's functional and performance specifications. Upon confirmation of failure, each product will be analyzed, by whatever means necessary, to determine the root cause of failure. If the root cause of failure is found to be not covered by the above provisions, then the product will be returned to the customer with a report indicating why the failure was not covered under the warranty.

This warranty does not cover defects, malfunctions, performance failures or damages to the unit resulting from use in other than its normal and customary manner, misuse, accident or neglect; or improper alterations or repairs. Cactus Technologies® Limited may repair or replace, at its discretion, any product returned by its customers, even if such product is not covered under warranty, but is under no obligation to do so.

IV. RECEIVING WARRANTY SERVICE

According to Cactus Technologies® warranty procedure, defective product should be returned only with prior authorization from Cactus Technologies® Limited. Please contact Cactus Technologies® Customer Service department (tech@cactus-tech.com) with the following information: product model number and description, nature of defect, conditions of use, proof of purchase and purchase date. If approved, Cactus Technologies® will issue a Return Material Authorization or Product Repair Authorization number and instructions to ship the product back to us for service.